

SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520CGCK09

Features

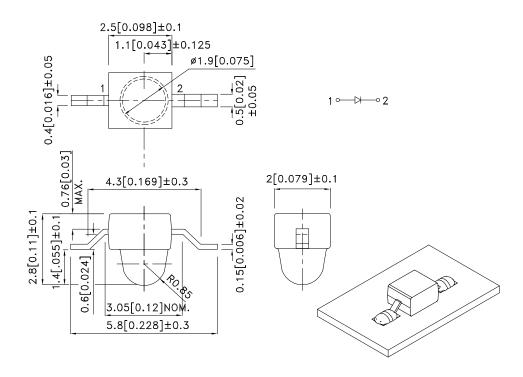
- Subminiature package.
- Z-bend lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package: 1000pcs / reel.
- RoHS compliant.

Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Green

Package Dimensions



- All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAC3400 **REV NO: V.5** DATE: APR/16/2010

CHECKED: Allen Liu

DRAWN: Y.F.Lv



ERP: 1202000450

APPROVED: WYNEC

Selection Guide

Part No.	Dice Lens Type		lv (mo @ 20	,	Viewing Angle [1]
			Min.	Тур.	201/2
AM2520CGCK09	Green (AlGaInP)	WATER CLEAR	280	700	20°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	20		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.1	2.5	V	IF=20mA
lR	Reverse Current	Green		10	uA	V _R =5V

Notes:

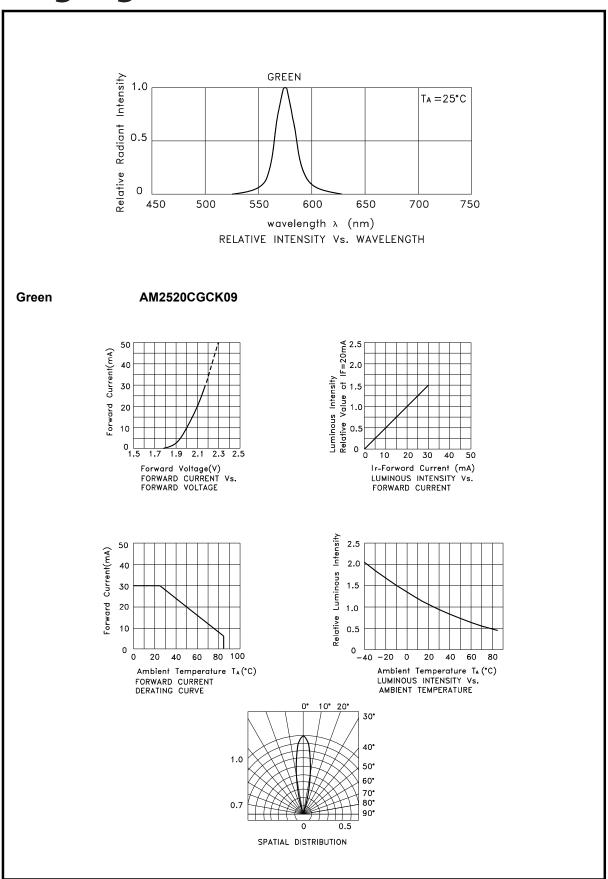
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	150	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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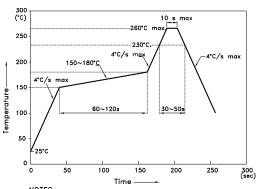
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AM2520CGCK09

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

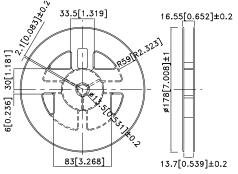
3.Number of reflow process shall be 2 times or less.

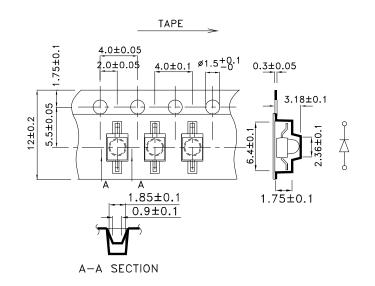
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

3.275 ø2 HOLE

Tape Dimensions (Units: mm)

Reel Dimension

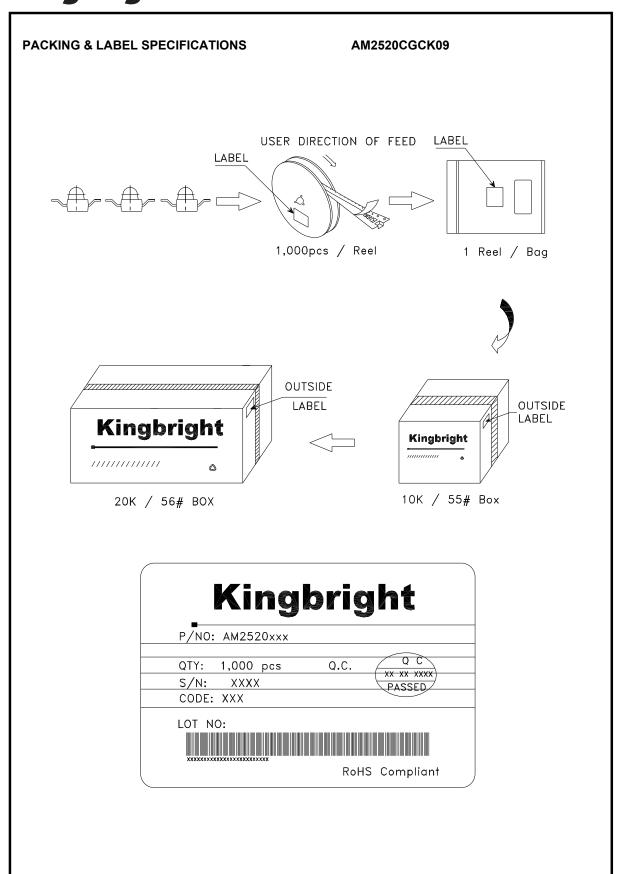




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